

ABSTRACT

A chip bonding apparatus includes a chip separation unit (100), a chip alignment unit (400), a chip bonding unit (300) and a bonding robotic arm unit. The bonding robotic arm unit comprises a first bonding robotic arm unit (200) and a second bonding robotic arm unit (500), the first bonding robotic arm unit including a first motion stage (210), a first driver (230) for driving the first motion stage, at least one first bonding robotic arm (220) disposed on the first motion stage, the first bonding robotic arm being used to extract a chip from the chip separation unit to transmit the same to the chip alignment unit; the second bonding robotic arm unit comprising a second motion stage (510), a second driver (530) for driving the second motion stage, and at least one second bonding robotic arm (520) provided on the second motion stage, the second bonding robotic arm being used to extract a chip from the chip alignment unit to transmit the same to the chip bonding unit. The chip bonding device realizes synchronization work of chip transmission, chip alignment and chip bonding and improves yield.